

ACM/IEEE INTERNATIONAL SYMPOSIUM ON LOW POWER  
ELECTRONICS AND DESIGN (ISLPED)  
Vienna, Austria, August 7-8, 2023

## 23<sup>rd</sup> International Low Power Design Contest

Submission Deadline: 11:59PM AoE, May 15, 2023

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The International Symposium on Low Power Electronics and Design (ISLPED) is holding the International Low Power Design Contest to provide a forum for showcasing design approaches and system solutions targeting power and energy-efficiency improvements. The goal is to encourage innovative design-oriented approaches for power reduction from both academic and industrial contributors. The accepted power-aware designs will be invited for presentations at ISLPED 2023 in a special session devoted to the Low Power Design Contest at the conference.

The presenting author of each selected design will be eligible for a 50% registration fee discount. Note that regular ISLPED papers still require at least one full registration per paper. Awards will be given for the best design based on the quality of the live demonstration and presentation.

The deadline for submissions is May 15, 2023 at 11:59pm AoE. The manuscript must be submitted electronically via the ISLPED submission website <https://softconf.com/n/islped2023-dc/>. If you have any questions regarding the contest please don't hesitate to [contact](#) our design-contest co-chairs. Acceptance and rejection notices will be emailed to the corresponding authors by June 20, 2023.

### Design-Contest Co-Chairs:

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<http://www.islped.org>

## CONTEST SUBMISSION GUIDELINES

- Submissions of **original designs developed at universities OR in industry are invited**. Designs submitted to previous ISLPED Design Contests are not eligible. Designs that have already received an award in other contests can be submitted but are not eligible for the ISLPED design contest award. Designs related to the regular papers submitted to ISLPED 2023 or published in other conferences after January 1, 2020 are also welcome. In such a case, the authors must include a reference to the corresponding paper in the demo proposal.
- A 2-page demo proposal is required and must be submitted prior to the deadline. Designs completed prior to January 1, 2021 are not eligible. The demo proposal should follow the format of a regular ISLPED conference paper and contain the title of the project, a 60-word abstract and a description of the design. The demo proposal will be distributed to the attendees of the conference. Refer to the following link for the paper template in MS Word or LaTeX format: <https://www.ieee.org/conferences/publishing/templates.html>
- Submissions may contain but are not limited to proof-of-implementation in the form of silicon chip, board or system photographs and software etc. An entry purely focusing on optimization techniques/algorithms/tools/simulations is not suitable for the contest. The submission should clarify the originality, distinguishing features, and the measured power/energy and performance metrics of the design. The power/energy targets of the design and the design choices, specific optimizations techniques and tradeoffs used to reduce power/energy need to be highlighted.
- Selected designs will be briefly presented at the Symposium in a **special session**. **An in-person demonstration during the conference is also mandatory**, and the **final design contest award** will be selected based on the demonstration and the presentation. The 2-page description of accepted demos will not be published in the ISLPED conference proceedings so that the authors can re-submit the related papers to other conferences. Yet, the demo description will be distributed to the attendees of the conference unless explicitly requested otherwise by the authors.